



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Cheng-Lien Chiang
Assignee: Bridge Semiconductor Corporation
Title: THREE-DIMENSIONAL STACKED SEMICONDUCTOR
PACKAGE DEVICE WITH BENT AND FLAT LEADS AND
METHOD OF MAKING SAME
Serial No.: 10/695,564 Filed: October 28, 2003
Examiner: Williams, A. Group Art Unit: 2826
Atty. Docket No.: BDG005-6

700 Sheet

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE

In response to the Office Action dated August 31, 2004, please amend the application as follows.

The Title Amendments begin at page 2.

The Specification Amendments begin at page 3.

The Claim Amendments begin at page 6.

The Remarks begin at page 31.

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